Ultra High Performance BGA Cooling Solutions w/ maxiGRIP™ Attachment*

DIGI-KEY PART # ATS1030-ND

ATS PART # ATS-50425G-C2-R0

Features & Benefits

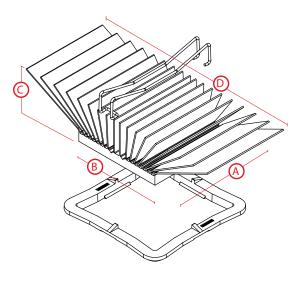
maxiFLOW[™] design features a low profile, spread fin array that maximizes surface area for more effective convection (air) cooling

maxiGRIP™ attachment applies steady, even pressure to the component and does not require holes in the PCB

Meets Telcordia GR-63-Core Office Vibration; ETSI 300 019 Transportation Vibration; and MIL-STD-810 Shock and Unpackaged Drop Testing standards

Comes preassembled with high performance thermal interface material

Designed for standard height components from 3 to 4.5mm





Thermal Performance Table AIR VELOCITY THERMAL RESISTANCE FT/MIN M/S °C/W (UNDUCTED) °C/W (DUCTED) 2.4 2 200 1.0 1.9 300 1.5 1.7 400 2.0 1.5 500 2.5 1.4 600 3.0 700 3.5 1.3 800 4.0 1.2

Product Details[†]

DIMENSION A	DIMENSION B	DIMENSION C [§]	DIMENSION D	TIM [‡]	FINISH
42.5	42.5	12.5	72.84	C675	BLUE-ANODIZED

For further technical information, please contact Advanced Thermal Solutions, Inc. at **1-781-769-2800** or **www.qats.com**

* RoHS Compliant

‡ TIM = Thermal Interface Material

† Dimensions are measured in millimeters◆ Dimensions A & B refer to component size

S Dimension C = the height of the heat sink shown above

and does not include the height of the attachment method



To place an order, please visit www.digikey.com